

# Ion irradiation and analysis of SiC Schottky diodes



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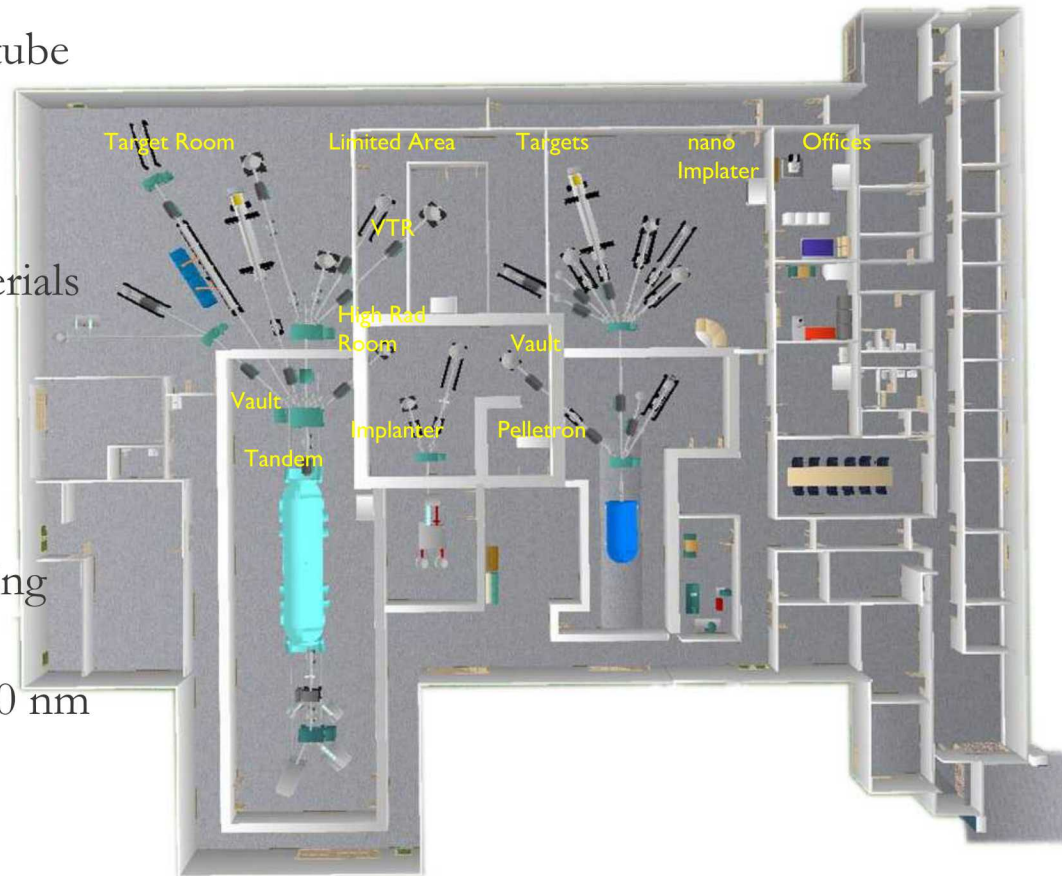
University of North Texas, October. 22 2019



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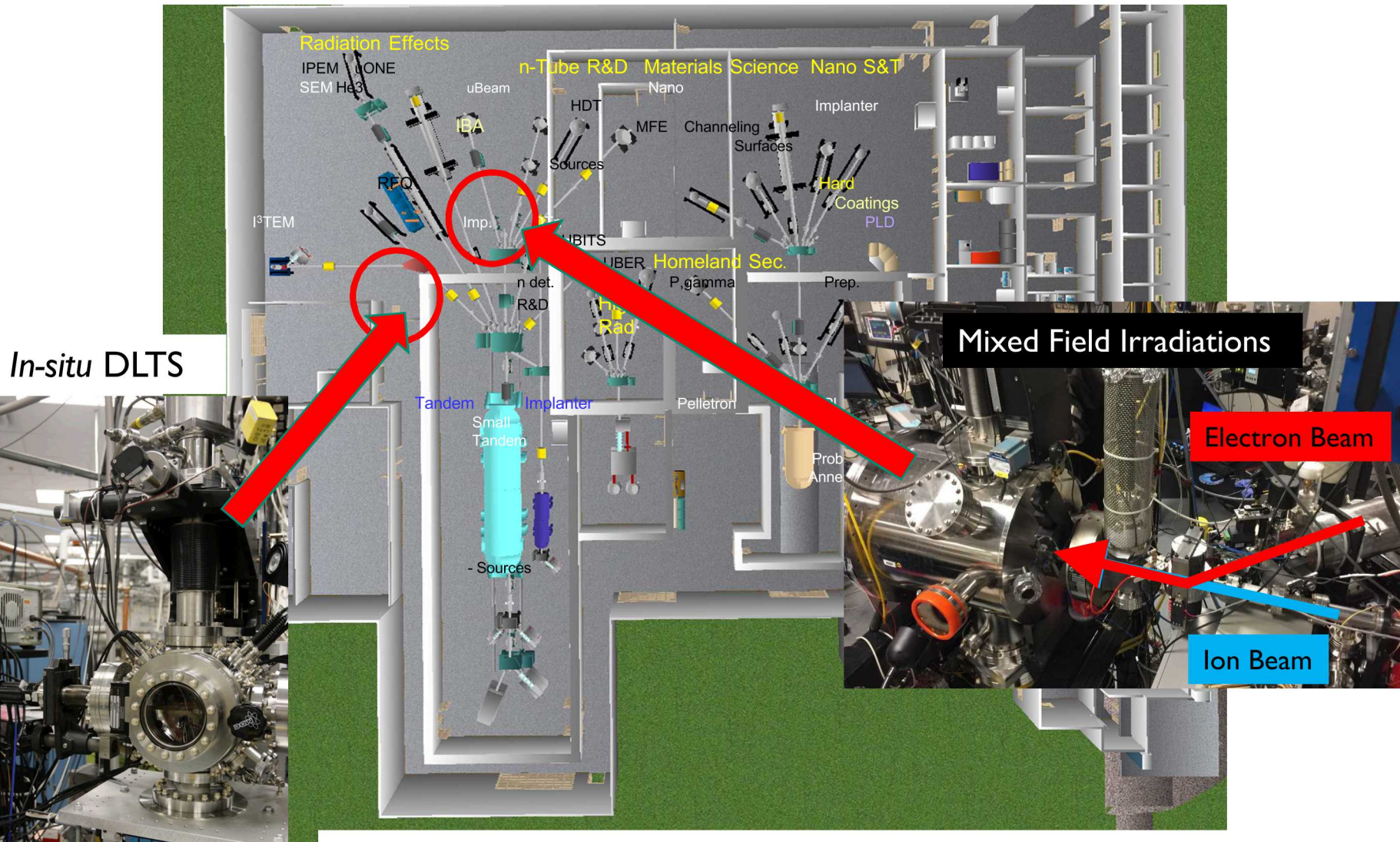
## Accelerators in the Ion beam Laboratory (IBL)

- **6 MV Tandem**
  - Radiation effects testing
  - Ion Beam Analysis (IBA) of neutron tube materials
- **3 MV Pelletron**
  - Ion Beam Analysis
  - Microbeam IBA of neutron tube materials
- **1 MV “Baby Tandem”**
  - Installation nearly complete
- **350 kV Implanter**
  - DT neutrons for detector calibration
  - DT neutrons for radiation effects testing
- **100 kV Nano-Implanter**
  - Focused ion beam lithography (sub -20 nm area)
  - Single atom device fabrication
- **30 kV He ion microscope**
  - 0.5 nm spot size





# Radiation Effects Testing



Probing basic mechanism of radiation effects from displacement damage through ionizing dose rates effects



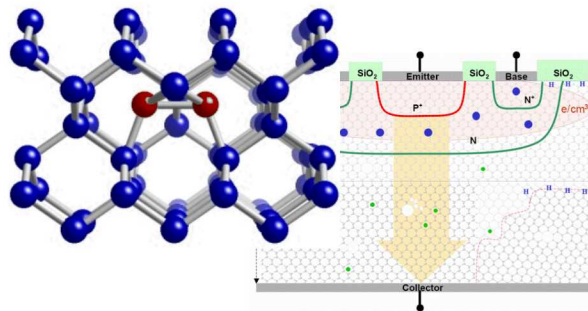


# Ions Simulate Neutron Effects

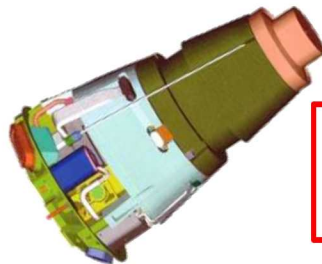
Substituting the primary knock-on atom of a neutron collision with MeV ions

# Defect Study Motivation – Displacement Damage

## Radiation Effects



Fundamental Radiation Induced Defects



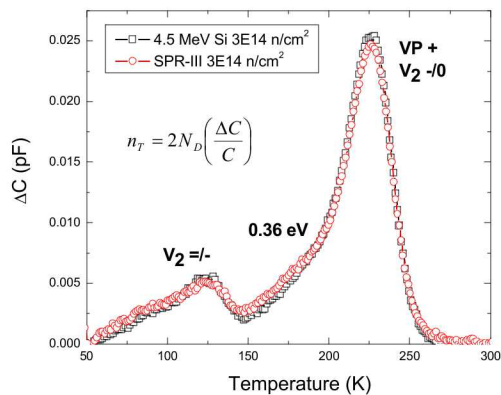
Of particular interest  
is early-time (<1 s) gain  
degradation

Degradation of Device/Circuit Performance

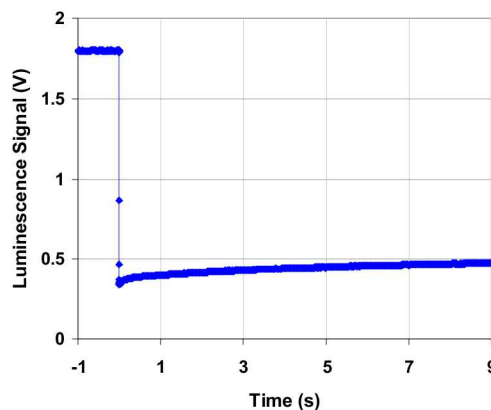
## Experimental Techniques at the Ion Beam Laboratory (IBL)

We use a series of *in-situ* techniques to explore the defect creation and annealing

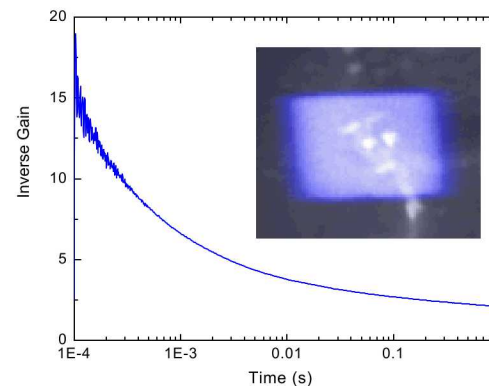
Deep-level Transient  
Spectroscopy (DLTS)



Photoluminescence

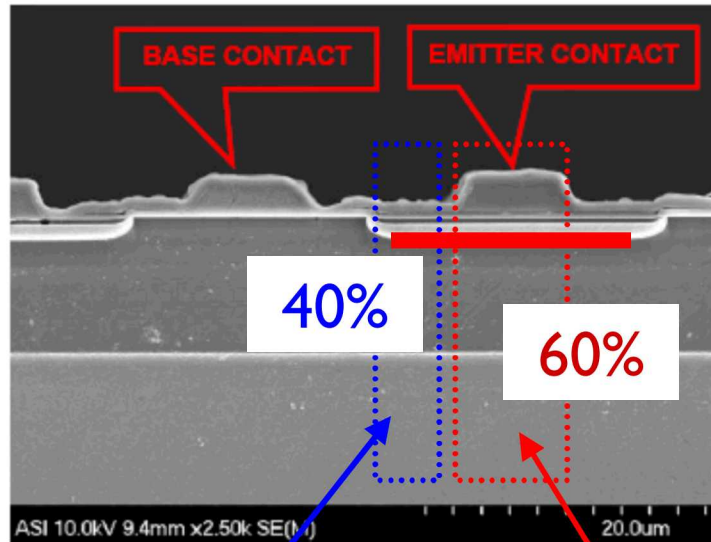


Active Gain



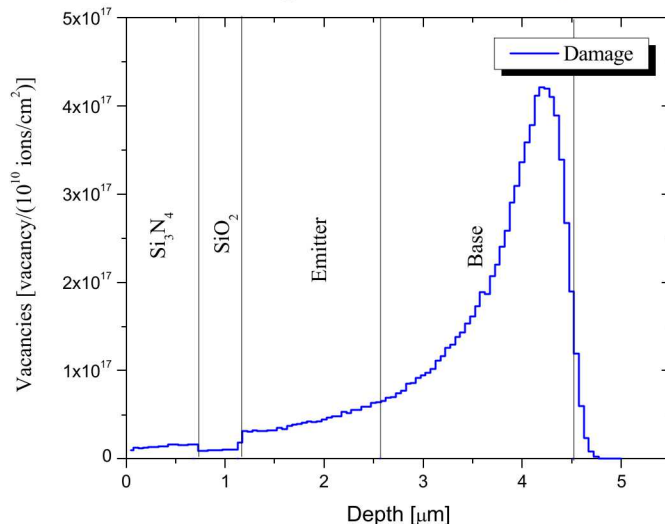
# SRIM-2003 Calculations for 10 MeV Si 3+

Critical Region:  
Base-Emitter  
Junction for low  
emitter currents

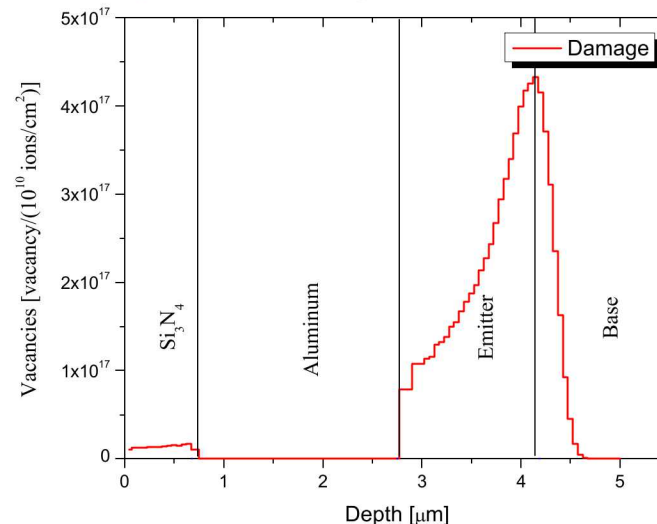


- Ions lose energy as they travel through the device
- Ion/energy combinations need to be tailored to specific device geometry

Ions through field oxide



Ions through emitter contact





## Messenger-Spratt damage constant

- The **damage constant** as determined from late-time gain degradation (Messenger-Spratt) is the same for all neutron irradiation facilities and we can scale the ion fluence to relate ion-to-neutron irradiation conditions.

## DLTS trap identification

- The **spectra of defects** as measured by DLTS in the base of pnp transistors that are responsible for the gain degradation are the same after neutron (including SPR-III and ACRR) and ion irradiations.

## DLTS trap quantification

- A given **number of defects**, as measured by DLTS in the base of a pnp transistor, produces the same late-time gain reduction for neutron (SPR-III) and ion irradiations.

## Annealing factor

- The SPR-III early-time **annealing factor** can be matched using ion irradiations (simulating a wide range of SPR-III fluence values).





Messenger and Spratt have shown that irradiation induced degradation of gain in BJTs is due to the reduced carrier lifetime through the base.

MS relation given by,

$$\frac{1}{\tau_f} - \frac{1}{\tau_i} \sim \frac{1}{G_f} - \frac{1}{G_i} \sim N_t \sim \varphi$$

$$DIG = \frac{1}{G_f} - \frac{1}{G_i} = k\varphi$$

$G_f$  and  $G_i$  are gain after and before irradiation

$\tau_f$  and  $\tau_i$  are minority carrier lifetimes through the base after and before irradiation

$N_t$  is the number of traps introduced to the device

$k$  is damage factor which quantifies damage per ion as a function of energy

$\varphi$  is ion fluence

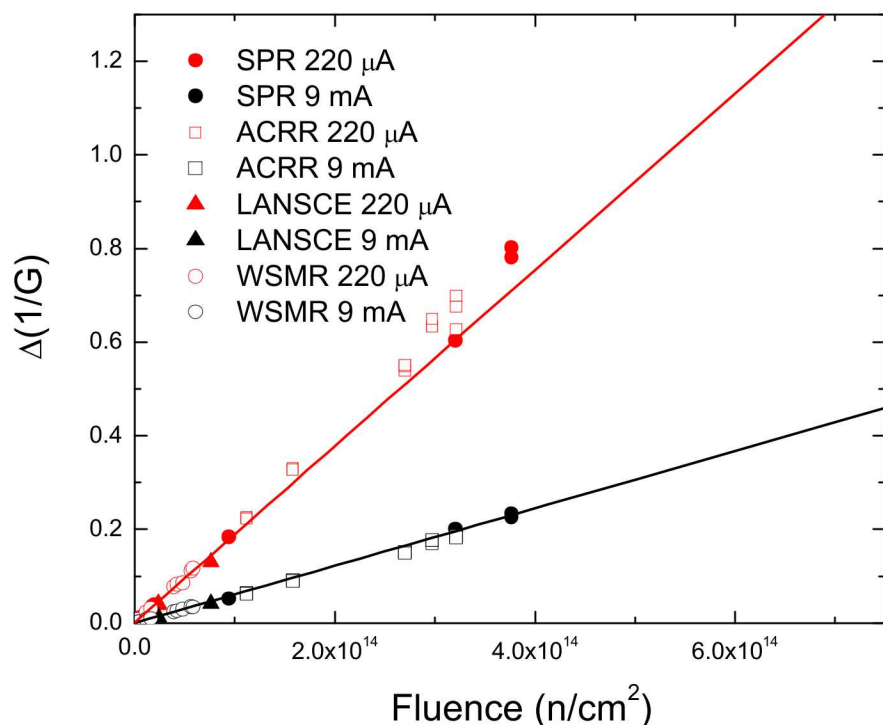


## 9 Late-Time Gain Comparison

- Displacement damage follows the Messenger-Spratt equation:

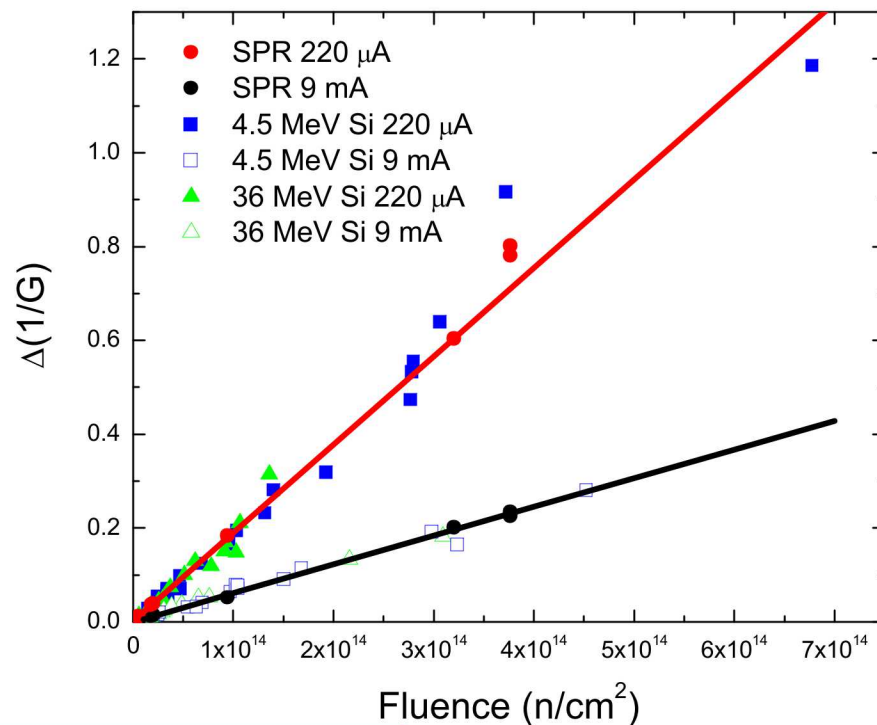
$$\frac{1}{G_{\infty}} - \frac{1}{G_0} = k \cdot \Phi$$

**Damage Constant**



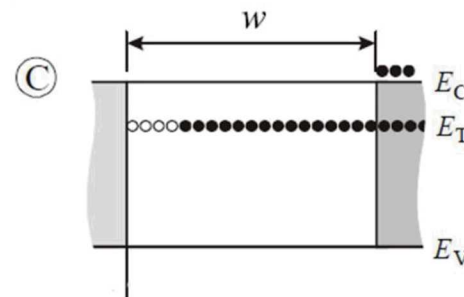
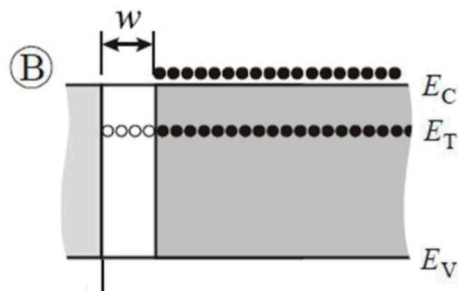
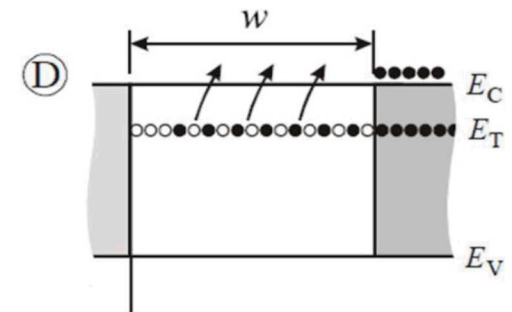
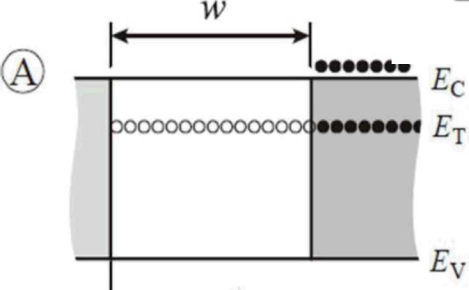
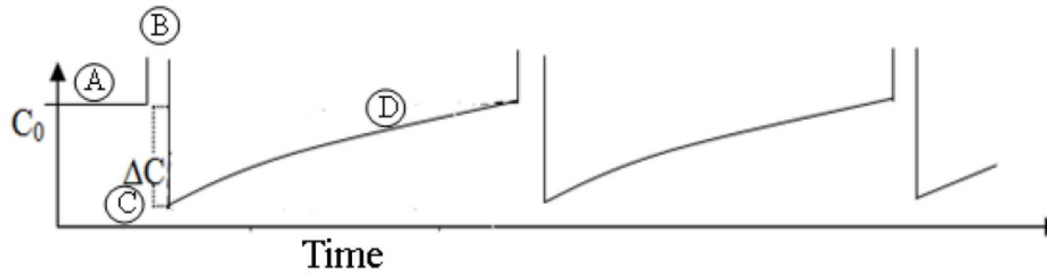
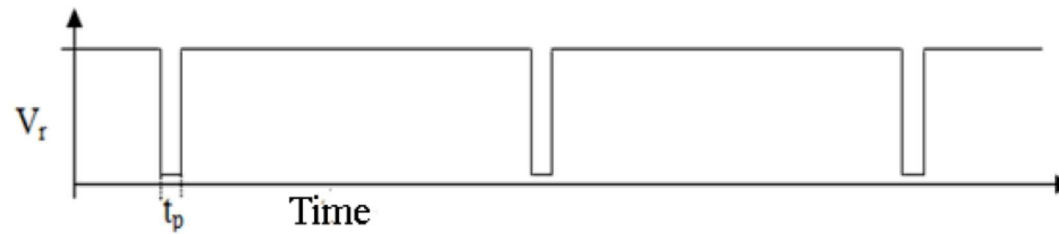
- Scale ion fluence to 1 MeV Neutron Equivalent Fluence using:

$$\Phi_{\text{neutron}} = \frac{k}{k_n} \cdot \Phi_{\text{ion}}$$

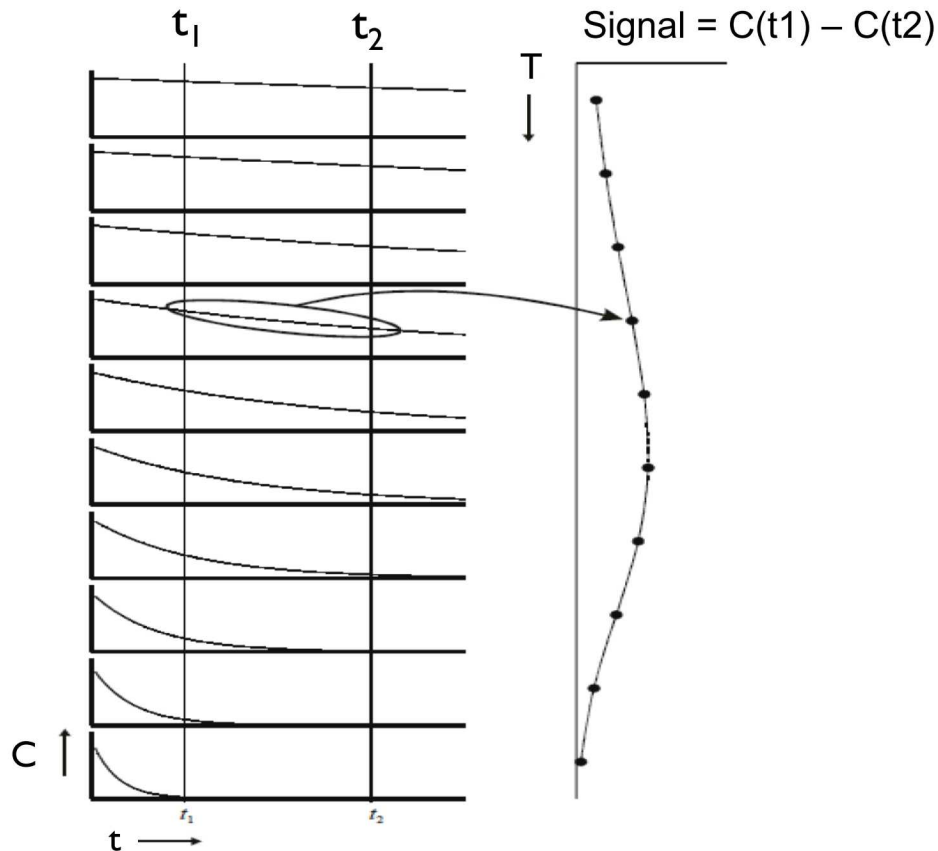


The **damage constant** as determined from late-time gain degradation (Messenger-Spratt) is the same for all neutron facilities. We can scale ion fluence to relate ion-to-neutron irradiation conditions.

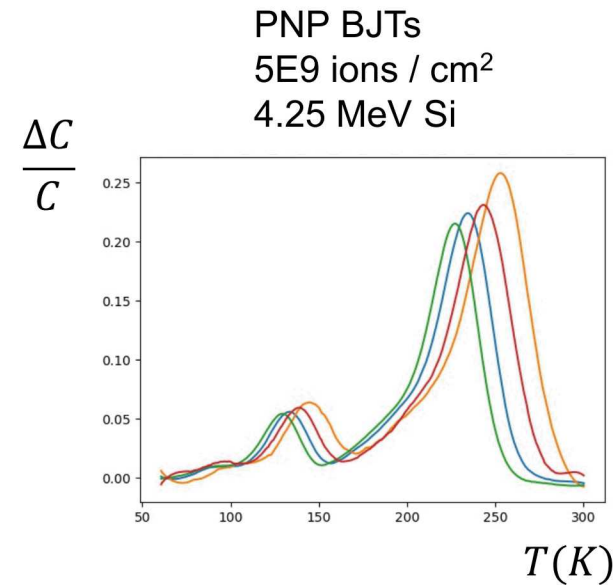
# DLTS Overview (Part I)



## DLTS overview (Part 2)



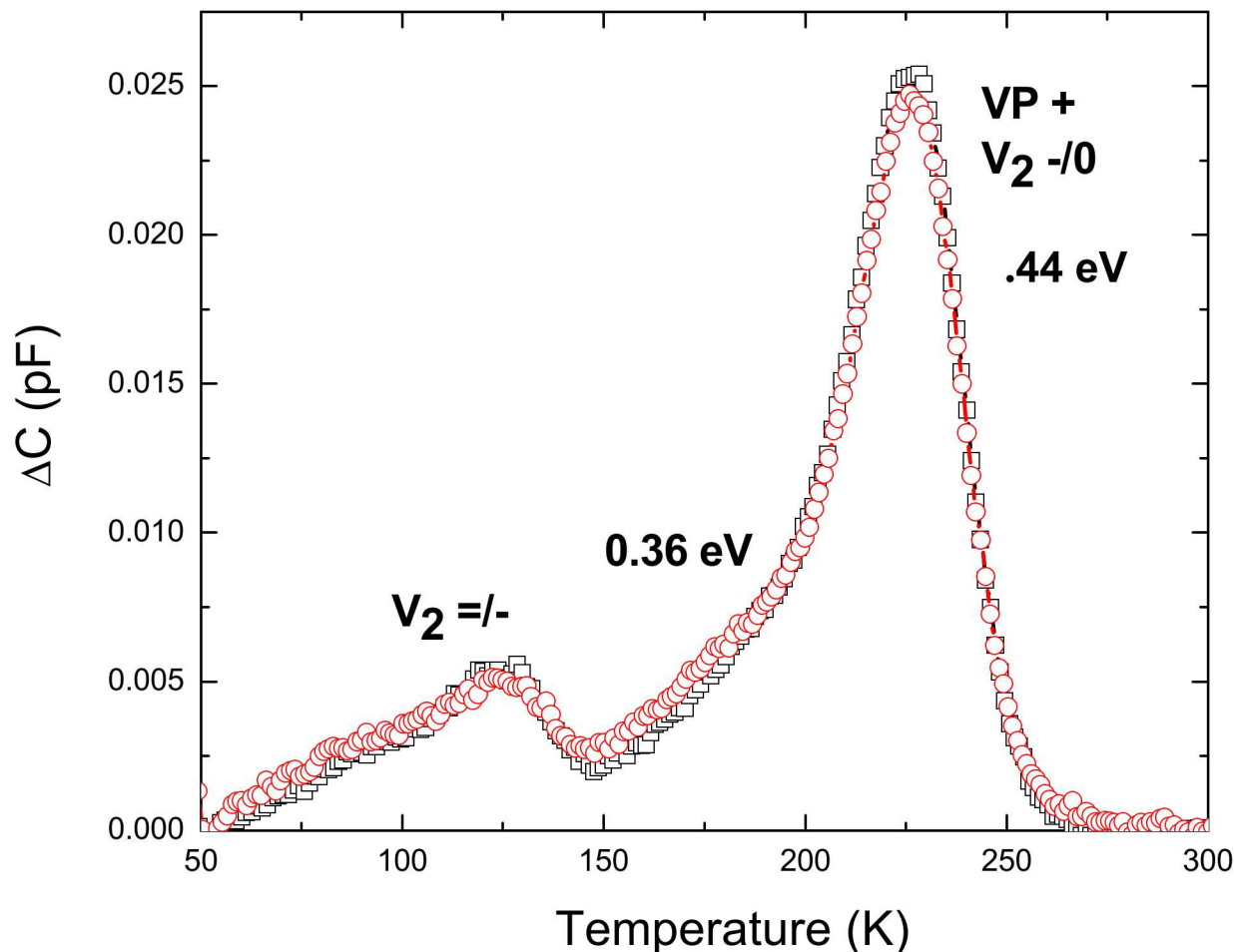
Rate of trapped carrier emission depends on temperature.



Multiple (4) boxcar averagers set to different "rate windows" record spectra.

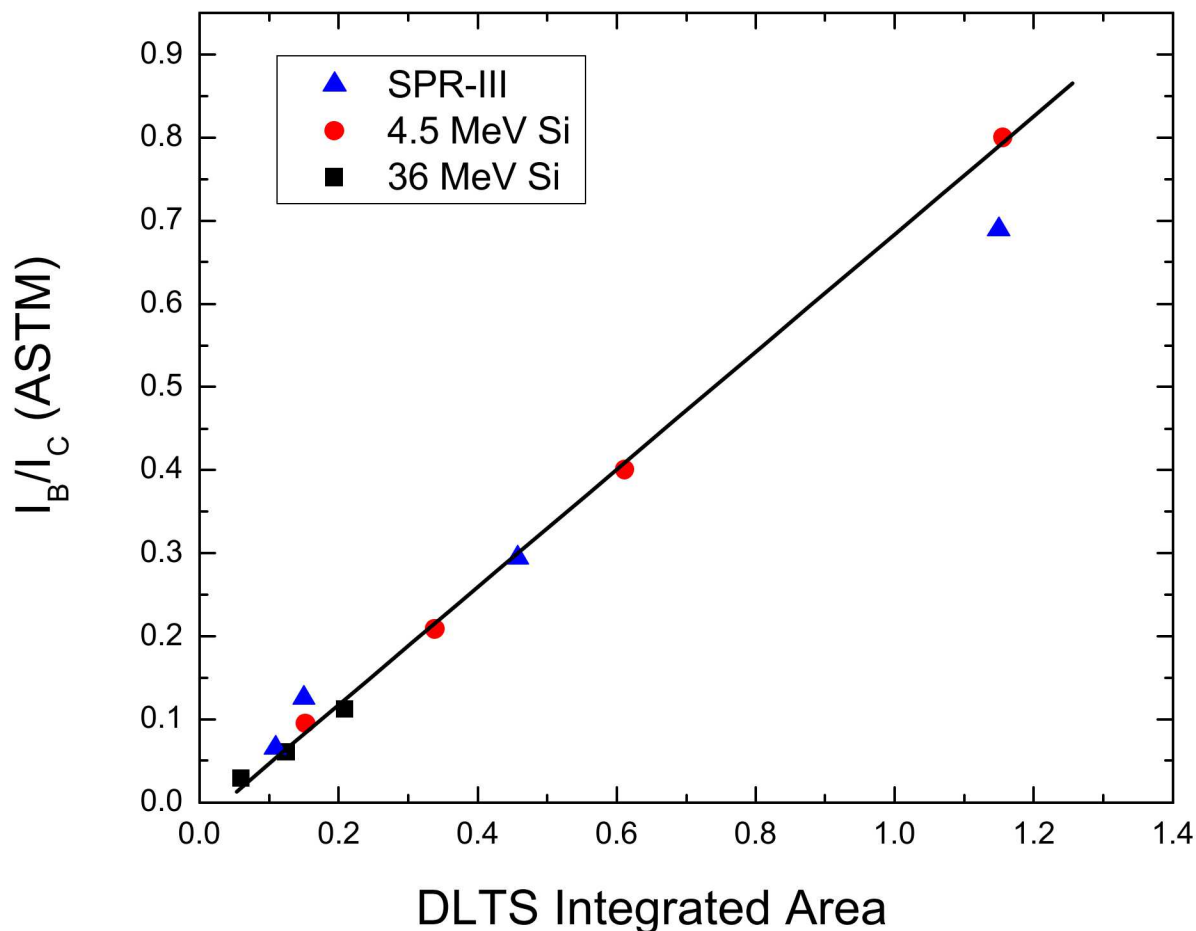


## Spectra of Defects: Ions and Neutrons



- DLTS peak amplitude proportional to number of traps
- Temperature scale provides a means to determine emission energy of the defect
- DLTS spectra of the base region of a PNP device.
- Probes the N-type area of the devices most closely associated with the BE junction.

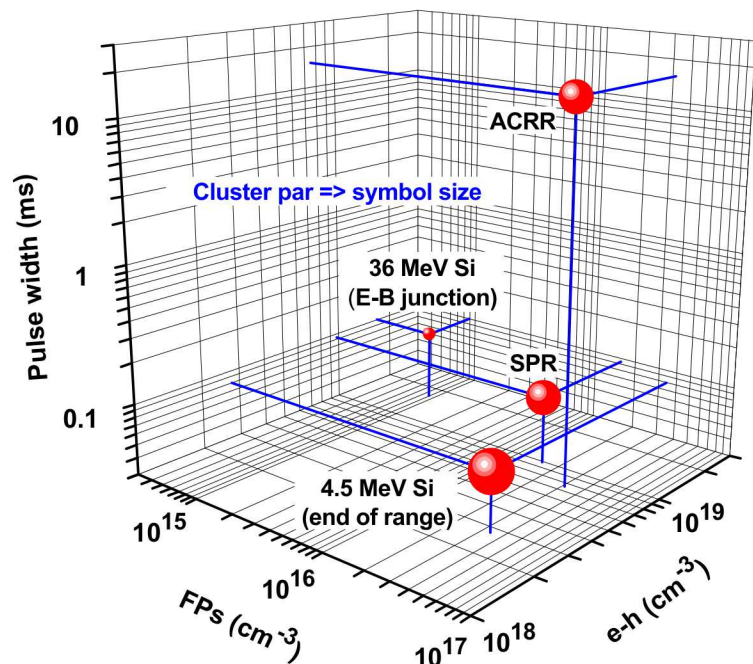
The **spectra of defects** in the base of pnp transistors are the same after neutron and ion irradiations.



- Integrated area of deep DLTS peaks
- Direct relationship between the DLTS area and the inverse gain degradation for ion neutron irradiations

A given **number of defects**, as measured by DLTS in the base of a pnp transistor, produces the same late-time gain reduction for neutron (SPR-III) and ion irradiations.

## Fast Neutron and Ion Facilities are used for early-time device response

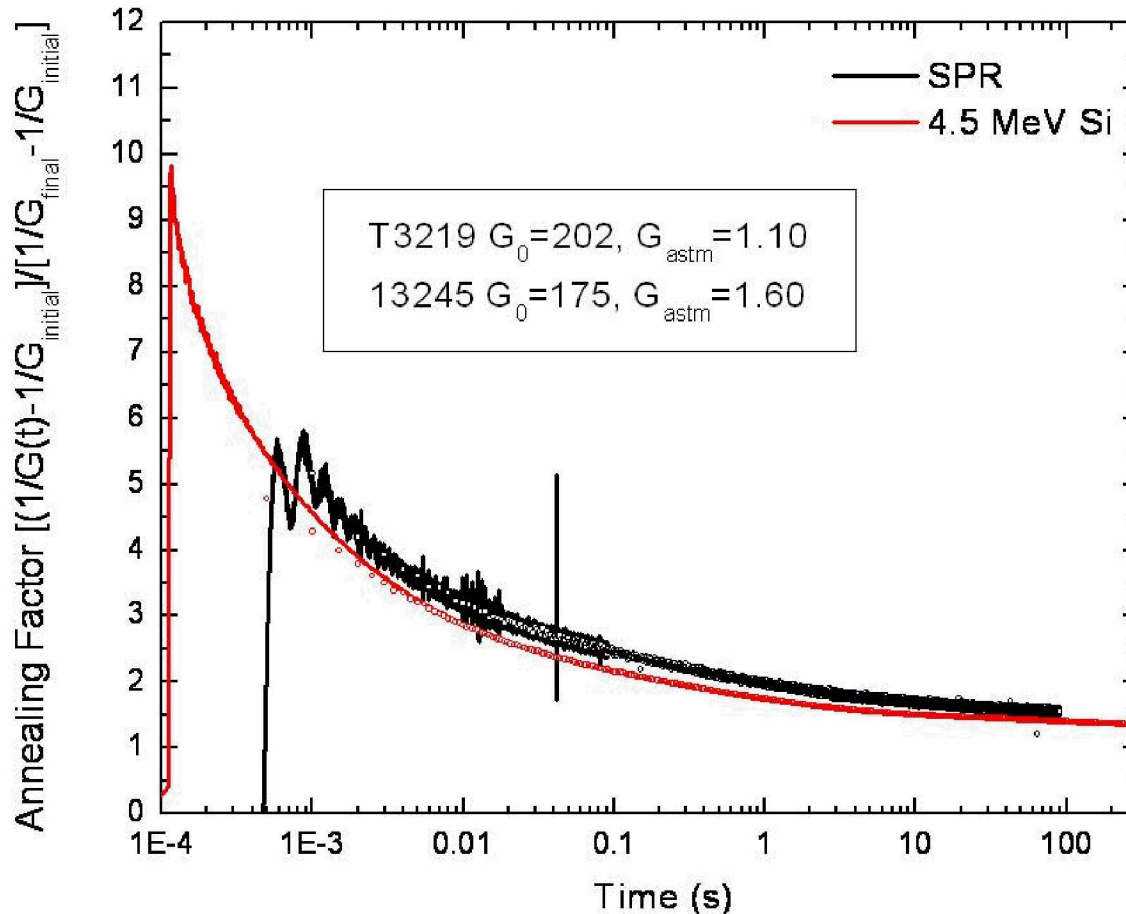


- SPR Shutdown September 30, 2006
- SPR Alternative Facilities
  - **Ion Beam Laboratory (IBL)**
    - Short pulse ion environment, High flux
  - **White Sands Missile Range FBR (WSMR)**
    - Short pulse Neutron Environment, Low flux
  - **Annular Core Research Reactor (ACRR)**
    - Late time neutron environment
  - **Little Mountain Test Facility (LMTF)**
    - Photocurrent, 2 – 30 MeV electron

We need the ion beam facility for high flux early time neutron simulations – we need to understand the **ion-to-neutron damage equivalence**



# Early-Time Annealing Factor Comparison



$$AF(t) = \frac{\frac{1}{G(t)} - \frac{1}{G_0}}{\frac{1}{G_\infty} - \frac{1}{G_0}} = \frac{N_t(t)}{N_t(\infty)}$$

The SPR-III early-time **annealing factor** can be matched using ion irradiations (simulating a wide range of SPR-III fluence values).



# SiC Schottky Diode Experiment

Measurements of early-time radiation effects

# SiC Schottky Diode Experiments - Motivation

Wide band gap materials provide high electric field strength, switching speed, and efficiency in radiation environments

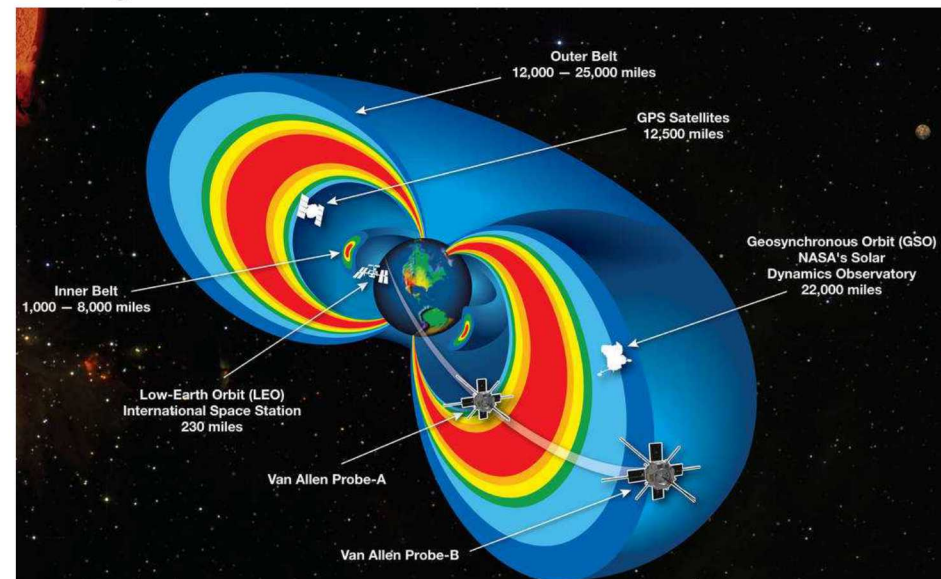
- Satellites and spacecraft
- Detectors for hadron colliders, fission and fusion reactors

Radiation Effects of Interest:

- Leakage current vs fluence from displacement damage
- Understanding mechanisms of room temperature annealing
- Early time effects ( $<1$  s)

We will use ion irradiation to simulate the neutron environment

- Allows access to early-time effects as ion irradiations lack the gamma environment of nuclear reactors





# Overview of Device

Cree/Wolfspeed SiC Schottky diode (C3D02060F)

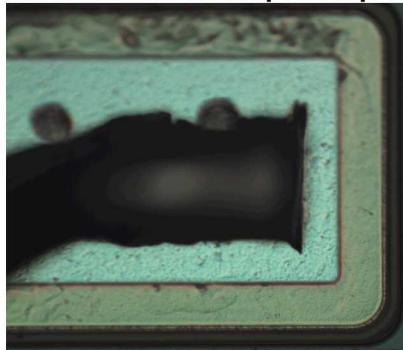
4H-SiC bandgap = 3.23 eV

4A, 600V COTS decapped to expose die

TO-220

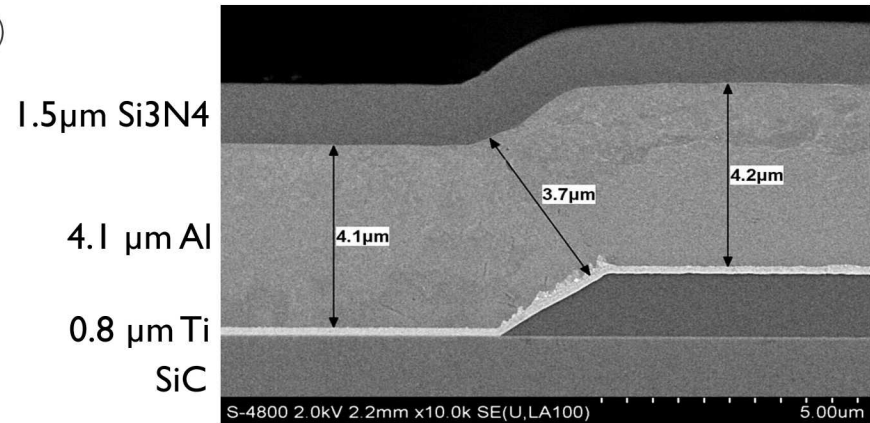


Jet etched to expose part

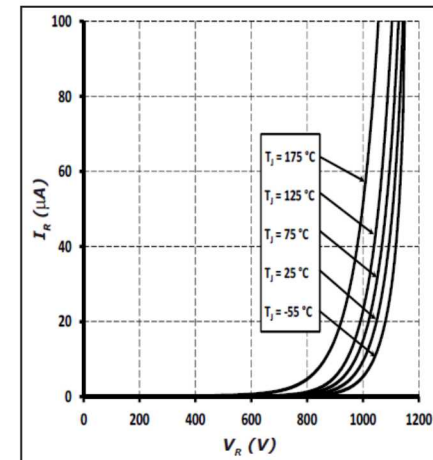


(To allow ion access)

SEM Cross-section of the die



Typical DC IV from spec sheet

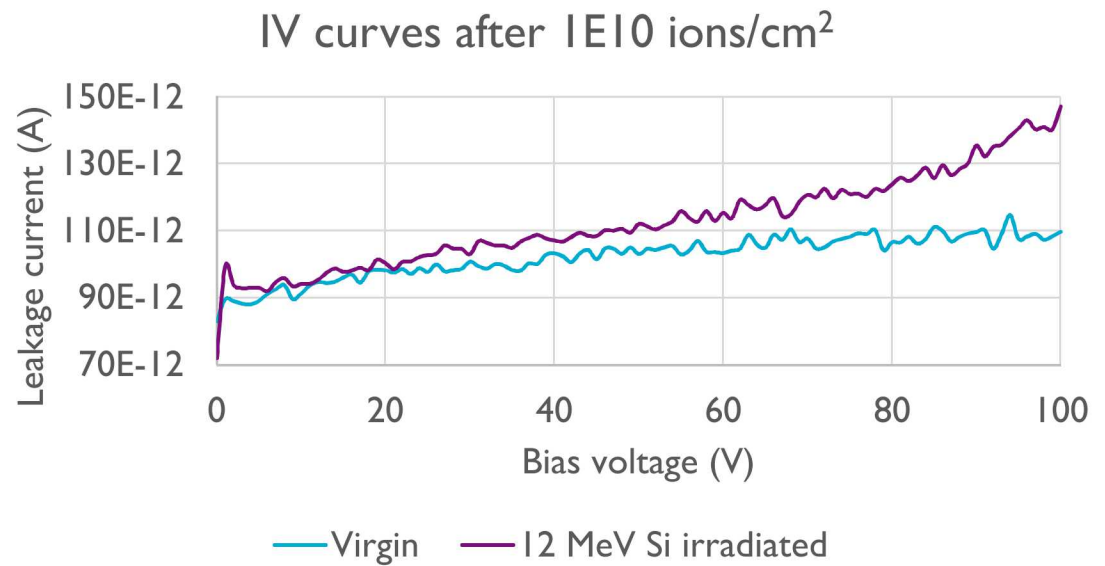
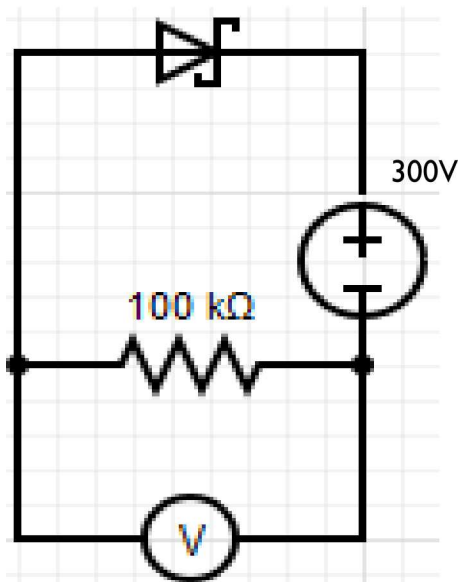


Vbreakdown > 600V

Ileakage (600V) << μA

# Leakage Current Measurement

- Diodes were reversed biased to 300 V in series with a 100 k $\Omega$  resistor
- Diodes were shot with 10 – 1000  $\mu$ s pulses of Si ions.



# Quantifying Ion Irradiation Damage (Displacement Damage)

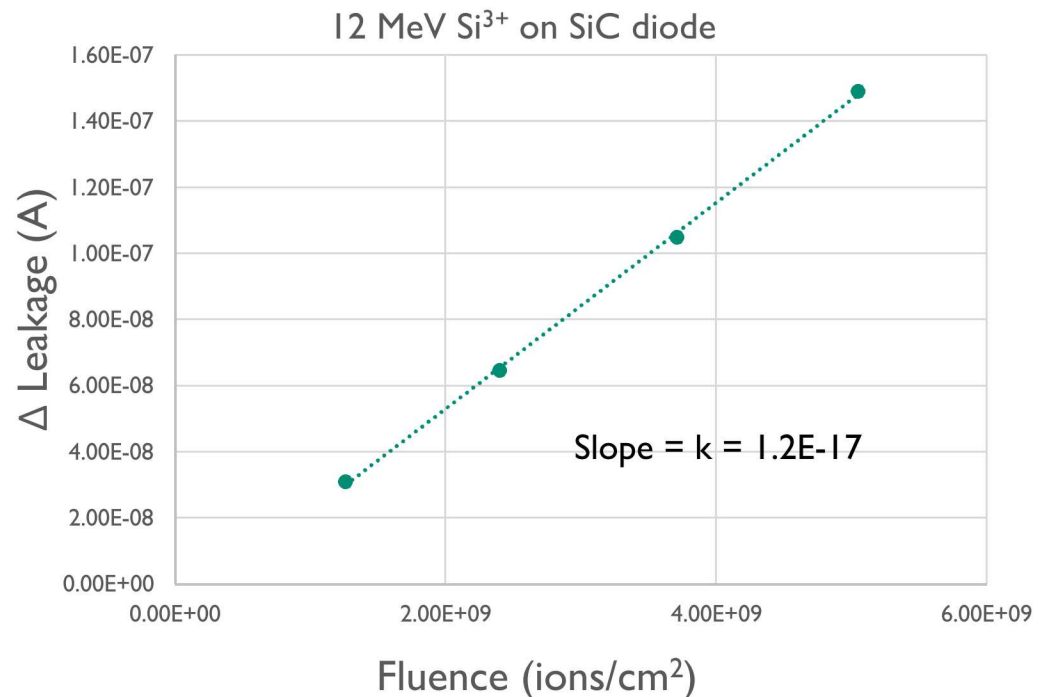
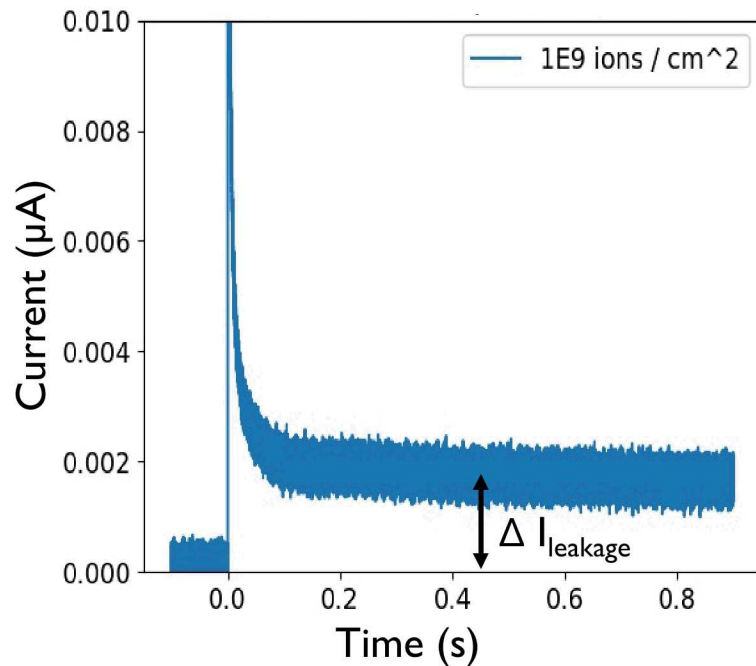
Schottky diode reverse bias leakage current is proportional to depletion region defects.

We use a k-factor relationship to quantify damage to the device under test.

- Analogous to Messenger–Spratt k-factor describing carrier lifetime

$$\Delta I_{leakage} \sim \frac{1}{\tau} - \frac{1}{\tau_0} \sim N_t \sim \varphi$$

$$\Delta I_{leakage} = k\varphi$$



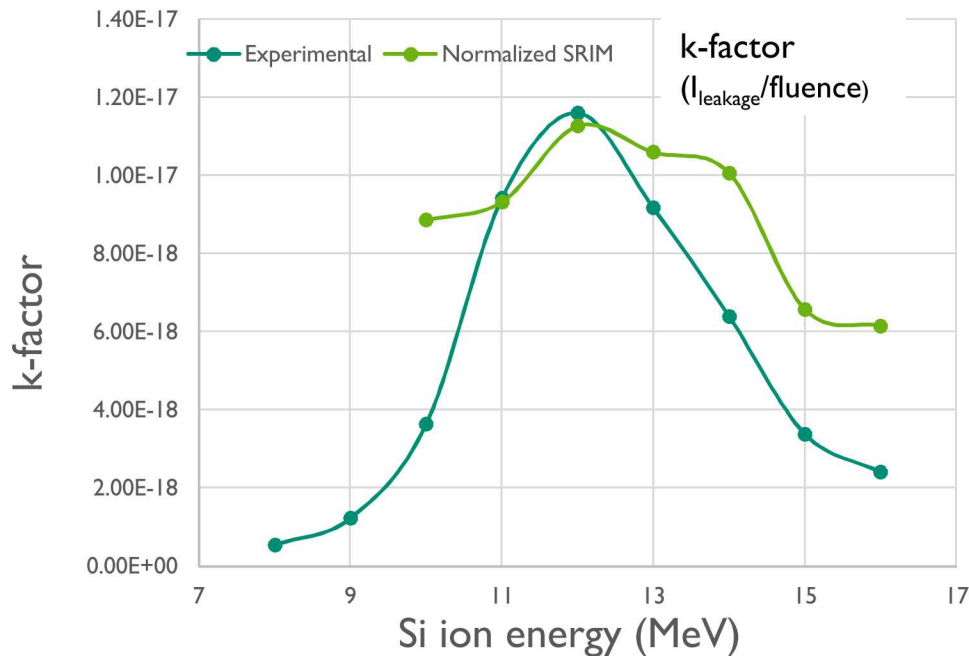


# Ion Energy to Simulate Neutron Irradiation

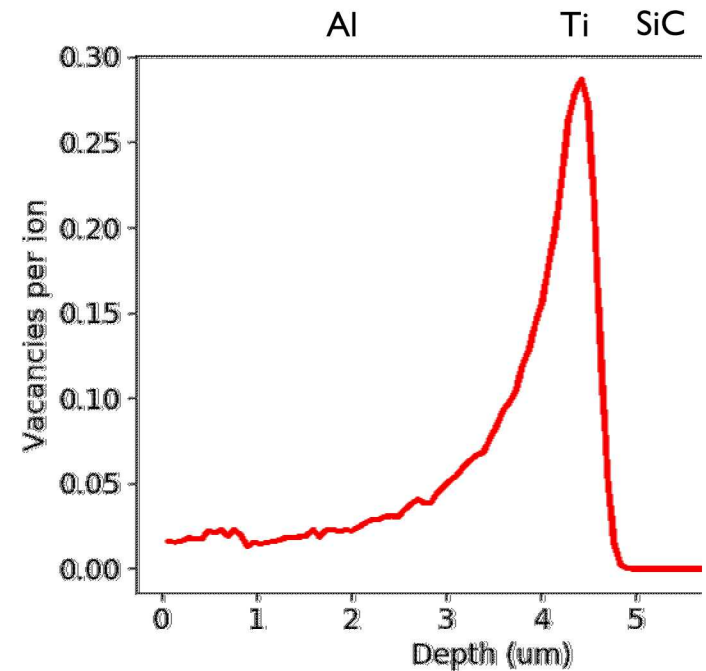
Si Ion energy varied at constant fluence

- Largest damage effect at 12 MeV → this is our End-of-Range condition which maximizes the damage
- Determined at a fixed time of 0.1 s after shots

Experimental and Predicted\* k-factors



\* Accounting only for vacancies produced within 100 nm of junction

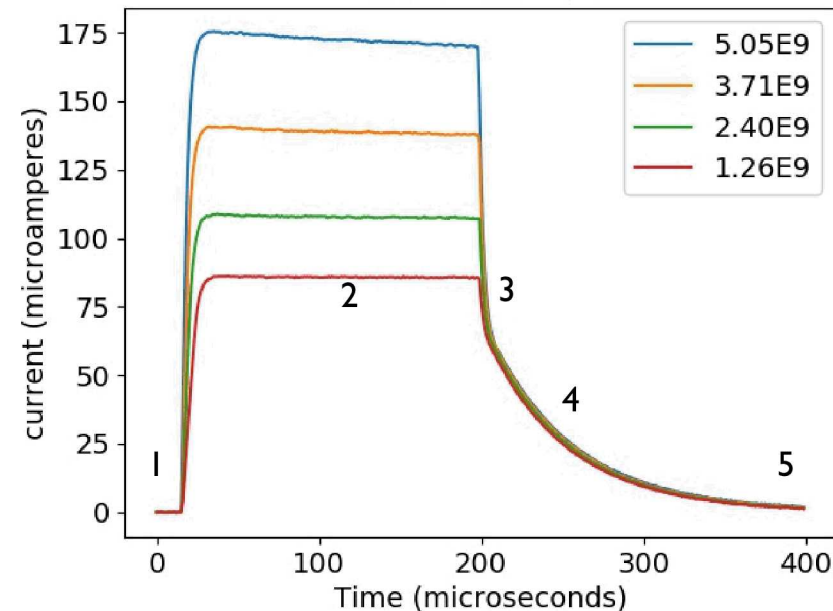


## Early-time ion response

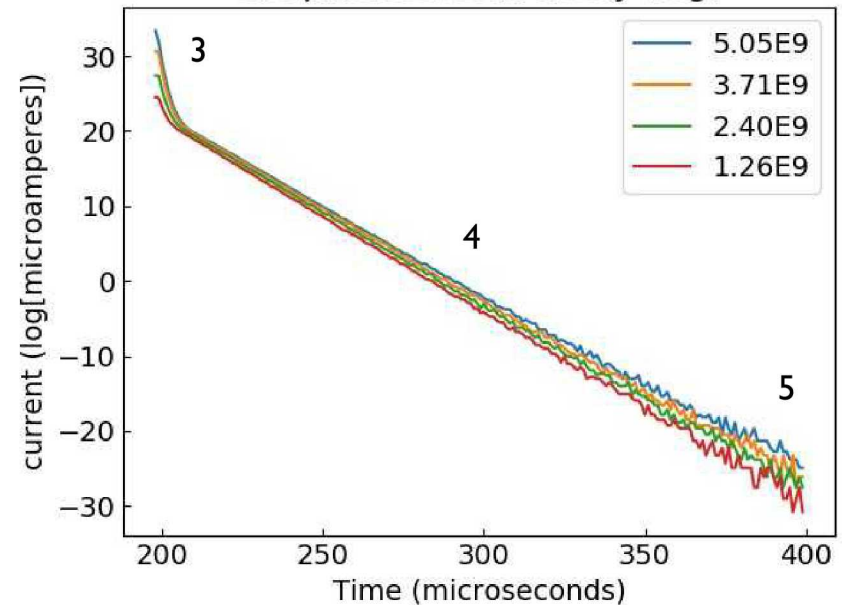
### Device Response Characteristics

- 1) Pre-shot leakage
- 2) Photocurrent during irradiation (proportional to flux)
- 3) Super-exponential, plasma enhanced recombination
- 4) Recombination, de-trapping
- 5) Late-time Annealing and leakage current

Early-time Photocurrent



SiC photocurrent decay (log)

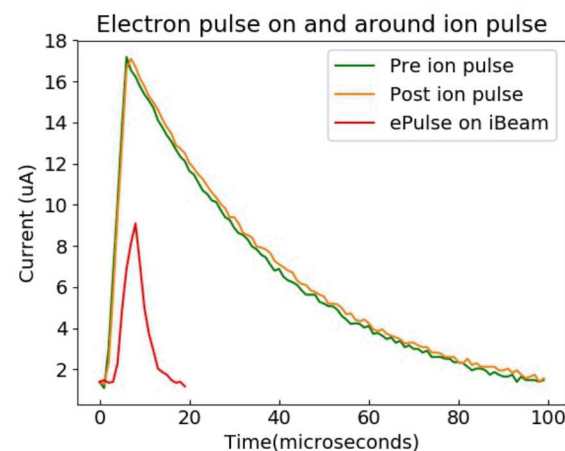
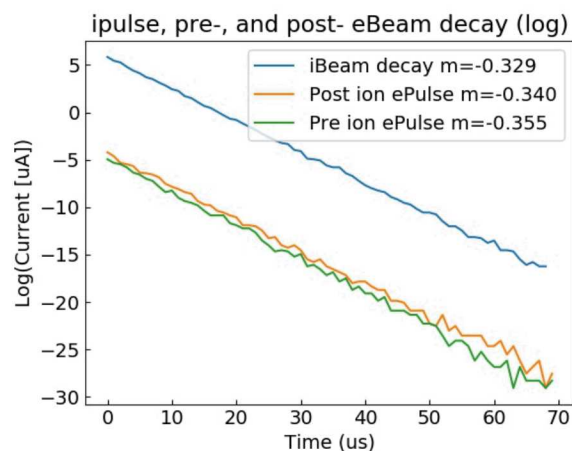
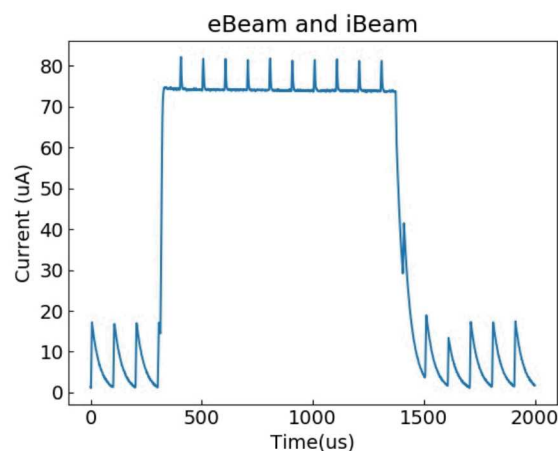


# Probing Early-Time Response With Electron Pulses

Use a short pulse electron gun to create e-h pairs (photocurrent without displacement damage)

Electron gun probes early-time effects of annealing and recombination by observing decay features

- We observe the same exponential fit for both the pre and post ion beam irradiation decay
  - $\tau = \frac{1}{m}$
  - Charge collection efficiency (CCE) degrades after multiple ion pulses
- During the ion irradiation we observe a super-exponential fit
  - Enhanced recombination and reduced amplitude due to plasma recombination



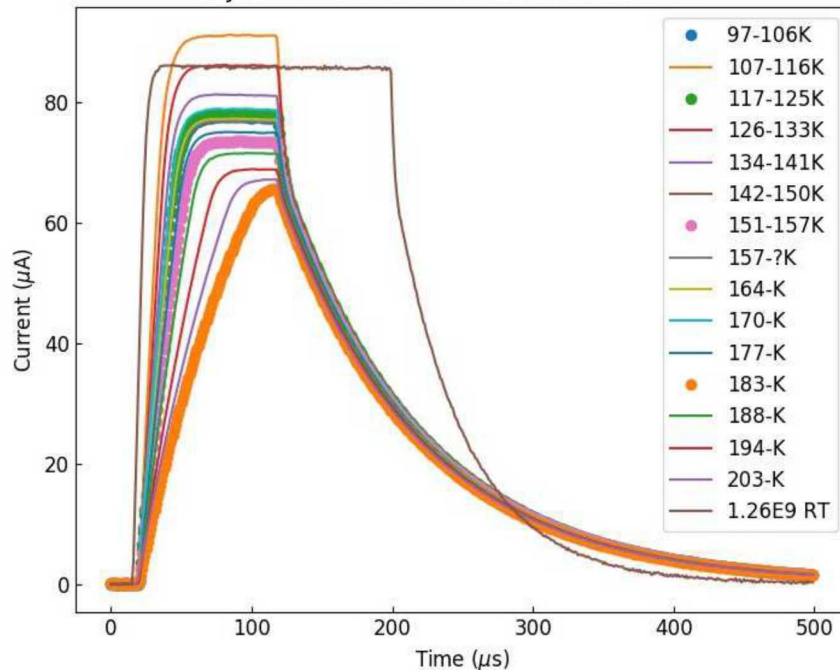
# Cryogenic shot

Intended to suppress thermal effects of carrier de-trapping

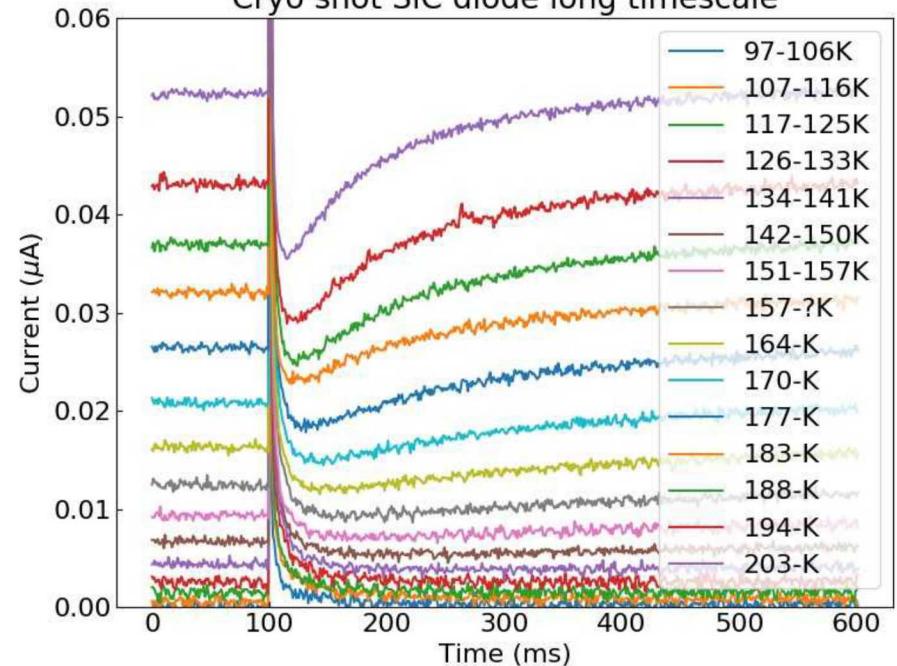
Expected to slow down processes to better understand early-time effects

Experiment provided more questions than answers

Cryo and RT SiC diode fast. Outliers dotted.

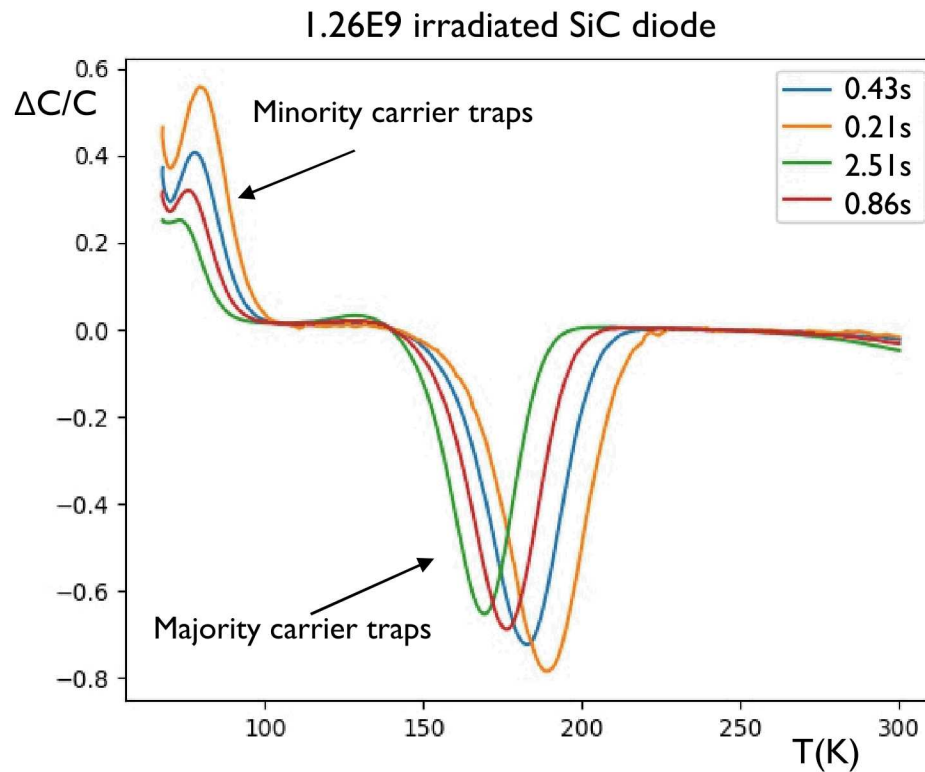


Cryo shot SiC diode long timescale





Initial DLTS studies are underway



- Observe both minority and majority carrier traps
- We observe a decrease in trap concentrations with increasing fluence

Why? Likely charge compensation, more work on-going!

# Conclusions

The IBL at SNL is equipment rich

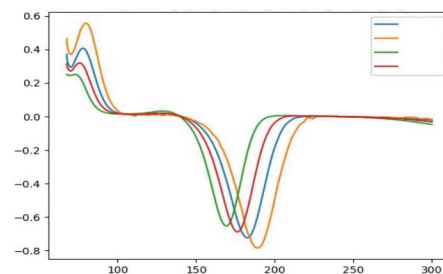
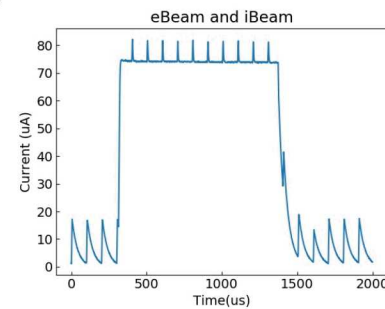
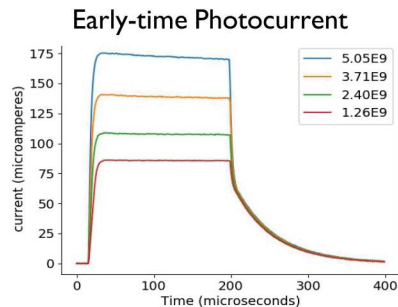
- But people poor

We can simulate neutron damage with ions

- Large equivalent flux
- Greater cross section than neutrons

On-going SiC SD study

- Three distinct post-irradiation features
- Experiments, analysis, modeling on-going



## Advertisement

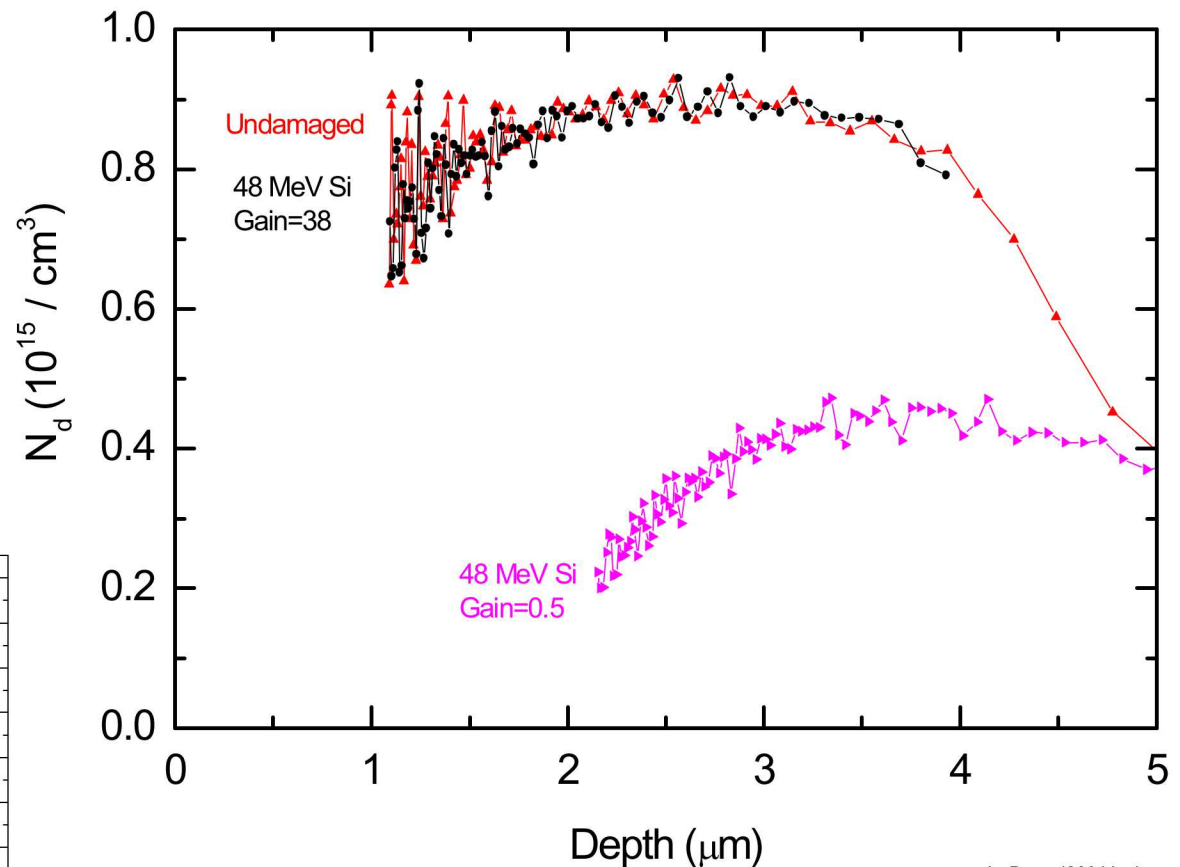
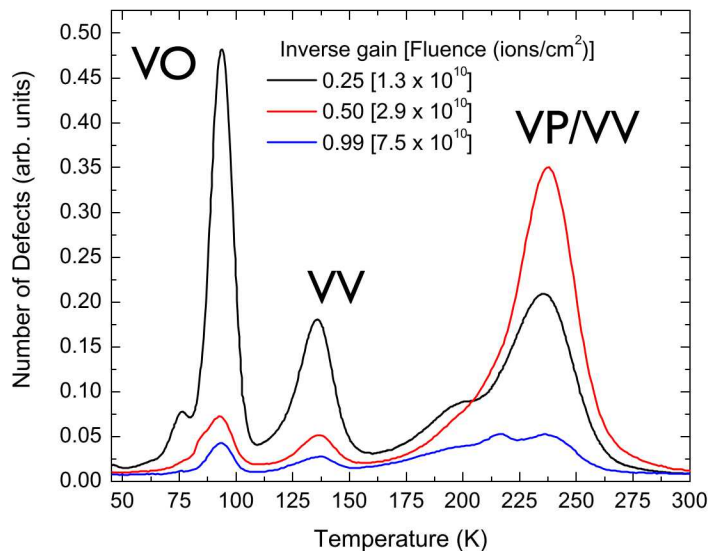
SNL IBL is opening positions for 2 more postdocs

- Mixed field irradiations
- D-T neutron experimentation and modeling



# Heavy Ion to Neutron Equivalence: SPR

Heavy ions: linear behavior at high fluence values

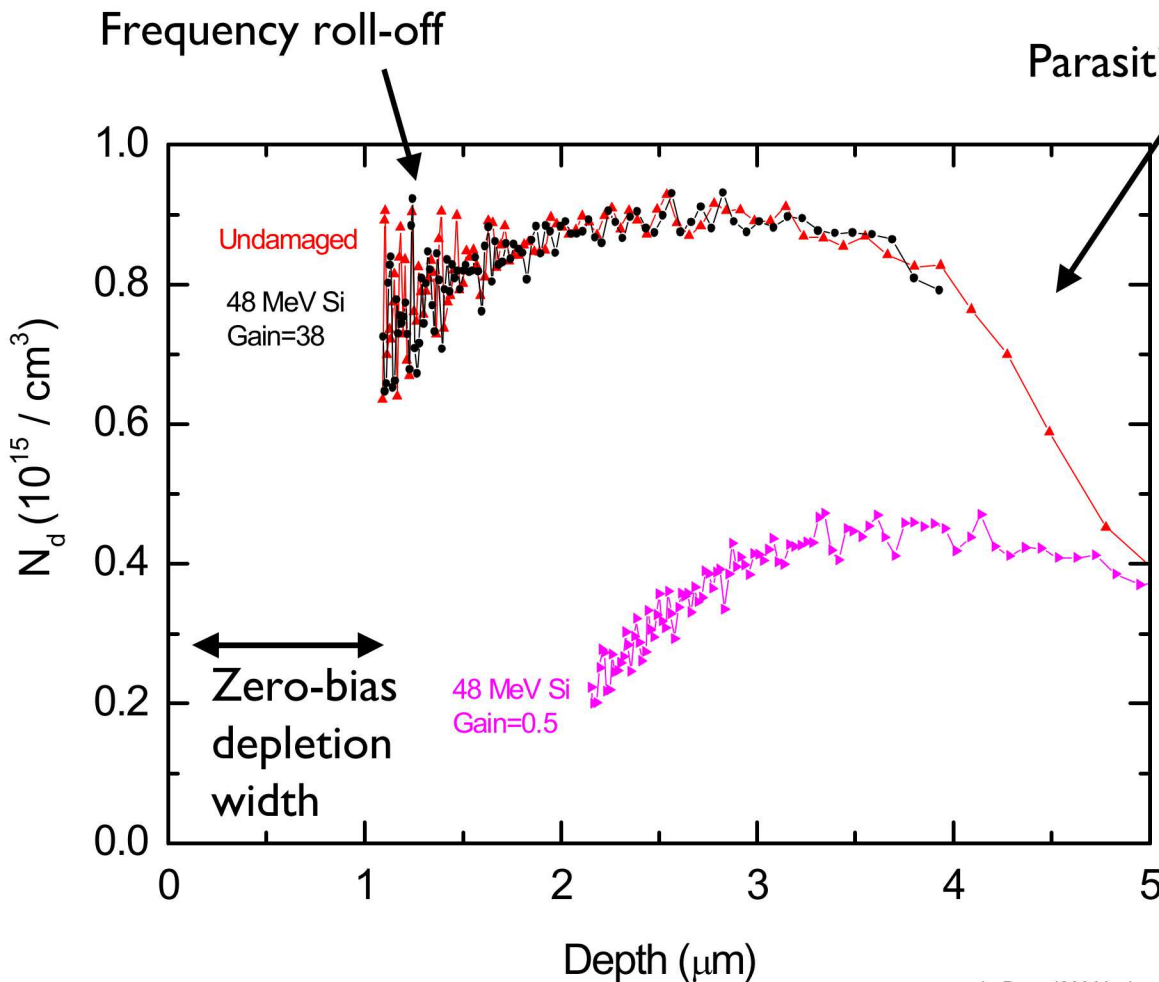


IonBeam 48 MeV.opj

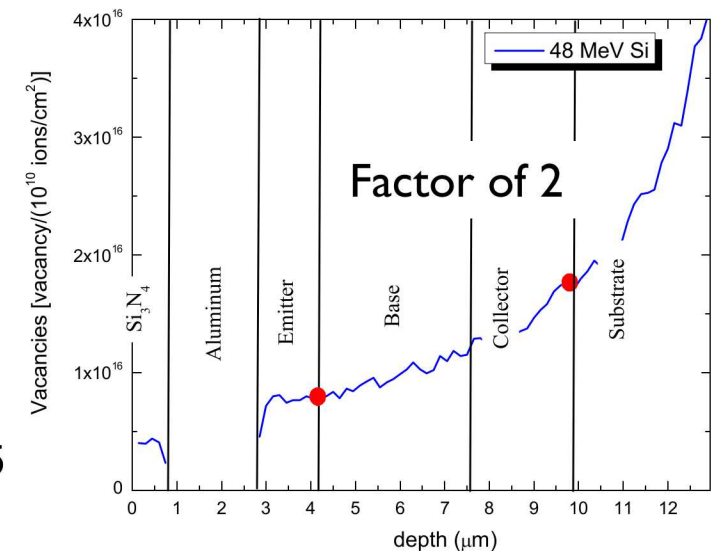
For high fluence we observe a change in the doping profile of the collector, and in the zero-bias depletion width.



# Base-Collector Junction Capacitance

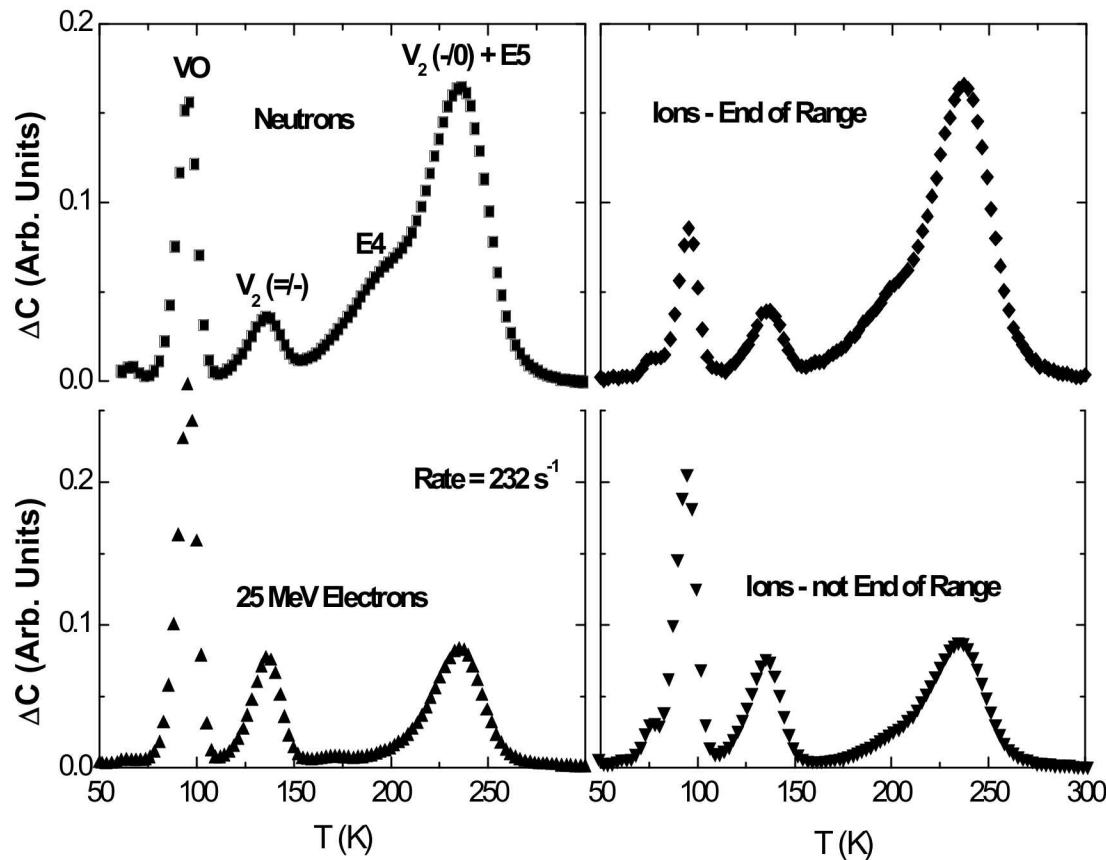


For high fluence we observe a change in the doping profile of the collector, and in the zero-bias depletion width.



# DLTS - Basic science technique to explore defect properties

## Clustered damage produces larger single-acceptor $V_2$



Uniquely identify and count the type and number of fundamental defects caused by irradiation

- Extended from diodes to actual devices (BJT's)
- Enabled study of clustered defects (neutrons and ions) - **R. M. Fleming, et al, JAP, 102, 043711 (2007)**
- This has led to discoveries of new Si defects - Strained and bistable  $V_2$  defects in damage clusters
- Bistable  $V_2$ -like defect can be used as a tool to de-convolve VP and  $V_2$  in the BJT base - **R. M. Fleming, et al, JAP, 108, 063716 (2010)**

